# 2-Input NAND **Schmitt-Trigger**

The MC74VHC1G132 is a single gate CMOS Schmitt NAND trigger fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The MC74VHC1G132 input structure provides protection when voltages up to 7V are applied, regardless of the supply voltage. This allows the MC74VHC1G132 to be used to interface 5V circuits to 3V

The MC74VHC1G132 can be used to enhance noise immunity or to square up slowly changing waveforms.

- High Speed: tpD = 3.6ns (Typ) at  $V_{CC} = 5V$
- Low Power Dissipation:  $I_{CC} = 2\mu A$  (Max) at  $T_A = 25$ °C
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays

June, 2000 - Rev. 3

- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300mA
- ESD Performance: HBM > 2000V

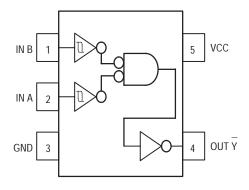


Figure 1. 5-Lead SOT-353 Pinout (Top View)

#### LOGIC SYMBOL





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#### **MARKING DIAGRAMS**





d = Date Code





Pin 1

d = Date Code

	PIN ASSIGNMENT						
1	IN B						
2	IN A						
3	GND						
4	OUT Y						
5	VCC						

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **FUNCTION TABLE**

Inp	uts	Output
Α	В	Y
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

#### **MAXIMUM RATINGS\***

Characteristics	Symbol	Value	Unit
DC Supply Voltage	VCC	-0.5 to +7.0	V
DC Input Voltage	VIN	-0.5 to +7.0	V
DC Output Voltage V <sub>CC</sub> = 0 High or Low State	VOUT	−0.5 to 7.0 −0.5 to V <sub>CC</sub> + 0.5	V
Input Diode Current	lıK	-20	mA
Output Diode Current (VOUT < GND; VOUT > VCC)	lok	+20	mA
DC Output Current, per Pin	lout	+25	mA
DC Supply Current, V <sub>CC</sub> and GND	Icc	+50	mA
Power dissipation in still air, SC-88A †	PD	200	mW
Lead temperature, 1 mm from case for 10 s	TL	260	°C
Storage temperature	T <sub>stg</sub>	–65 to +150	°C

<sup>\*</sup> Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

#### RECOMMENDED OPERATING CONDITIONS

Characteristics	Symbol	Min	Max	Unit
DC Supply Voltage	Vcc	4.5	5.5	V
DC Input Voltage	VIN	0.0	5.5	V
DC Output Voltage	Vout	0.0	Vcc	V
Operating Temperature Range	TA	-55	+125	°C

The  $\theta_{JA}$  of the package is equal to 1/Derating. Higher junction temperatures may affect the expected lifetime of the device per the table and figure below.

# DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

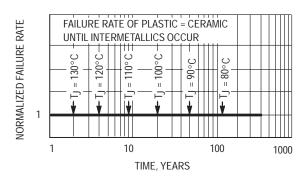


Figure 2. Failure Rate vs. Time Junction Temperature

<sup>†</sup>Derating — SC-88A Package: -3 mW/°C from 65° to 125°C

#### DC ELECTRICAL CHARACTERISTICS

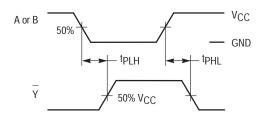
			VCC	1	A = 25°0	2	T <sub>A</sub> ≤	85°C	<b>T</b> <sub>A</sub> ≤ '	125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>T+</sub>	Positive Threshold Voltage		3.0 4.5 5.5	1.50 2.35 2.80	1.88 2.66 3.21	2.25 3.10 3.70	1.50 2.35 2.80	2.25 3.10 3.70	1.50 2.35 2.80	2.25 3.10 3.70	V
V <sub>T</sub>	Negative Threshold Voltage		3.0 4.5 5.5	0.65 1.10 1.45	1.03 1.62 2.02	1.40 2.10 2.60	0.65 1.10 1.45	1.40 2.10 2.60	0.65 1.10 1.45	1.40 2.10 2.60	V
VH	Hysteresis Voltage		3.0 4.5 5.5	0.30 0.40 0.50	0.85 1.05 1.20	1.60 2.00 2.25	0.30 0.40 0.50	1.60 2.00 2.25	0.30 0.40 0.50	1.60 2.00 2.25	V
VOH	Minimum High-Level Output Voltage IOH = -50μA	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -50μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		I <sub>OH</sub> = -4mA I <sub>OH</sub> = -8mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V <sub>OL</sub>	Maximum Low–Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 50μA	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		I <sub>OL</sub> = 4mA I <sub>OL</sub> = 8mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
IIN	Maximum Input Leakage Current	V <sub>IN</sub> = 5.5V or GND	0 to 5.5			±0.1		±1.0		±1.0	μА
ICC	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			2.0		20		40	μΑ

## AC ELECTRICAL CHARACTERISTICS ( $C_{load}$ = 50 pF, Input $t_r/t_f$ = 3.0ns)

				T <sub>A</sub> = 25°C			T <sub>A</sub> ≤	85°C	<b>T</b> <sub>A</sub> ≤ 125°C		
Symbol	Parameter	Test Condi	tions	Min	Тур	Max	Min	Max	Min	Max	Unit
tPLH, tPHL	Maximum Propogation Delay, A	V <sub>CC</sub> = 3.3 ± 0.3V	$C_L = 15 pF$ $C_L = 50 pF$		4.6 6.1	11.9 15.4	1.0 1.0	14.0 17.5	1.0 1.0	16.1 19.6	ns
	or B to Y	V <sub>CC</sub> = 5.0 ± 0.5V	$C_L = 15 pF$ $C_L = 50 pF$		3.6 4.3	7.7 9.7	1.0 1.0	9.0 11.0	1.0 1.0	10.3 12.3	
C <sub>IN</sub>	Maximum Input Capacitance				5.5	10		10		10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0V	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 1.)	11	pF

<sup>1.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub>+I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub>+I<sub>CC</sub> • V<sub>CC</sub>.



\*Includes all probe and jig capacitance

DEVICE

UNDER

TEST

Figure 3. Switching Waveforms

Figure 4. Test Circuit

OUTPUT

TEST POINT

 $\mathsf{C}_{\mathsf{L}^*}$ 

### **DEVICE ORDERING INFORMATION**

	Device Nomenclature							
Device Order Number	Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type (Name/SOT#/ Common Name)	Tape and Reel Size
MC74VHC1G132DFT1	MC	74	VHC1G	132	DF	T1	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1G132DFT2	MC	74	VHC1G	132	DF	T2	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1G132DFR2	MC	74	VHC1G	132	DF	R2	SC-88A / SOT-353 / SC-70	330 mm (13") 10000 Unit
MC74VHC1G132DTT2	MC	74	VHC1G	132	DT	T2	TSOPS / SOT-23 / SC-59	178 mm (7") 3000 Unit
MC74VHC1G132DTR2	MC	74	VHC1G	132	DT	R2	TSOPS / SOT-23 / SC-59	330 mm (13") 10000 Unit

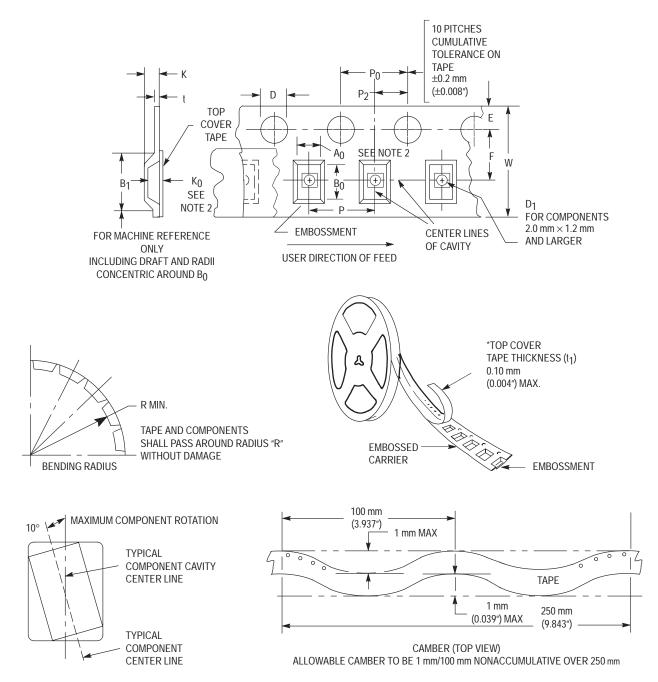


Figure 5. Carrier Tape Specifications

#### EMBOSSED CARRIER DIMENSIONS (See Notes 1 and 2)

Tape Size	B <sub>1</sub> Max	D	D <sub>1</sub>	E	F	К	Р	P <sub>0</sub>	P <sub>2</sub>	R	Т	w
8 mm	4.35 mm (0.171")	1.5 +0.1/ -0.0 mm (0.059 +0.004/ -0.0")	1.0 mm Min (0.039")	1.75 ±0.1 mm (0.069 ±0.004")	3.5 ±0.5 mm (1.38 ±0.002")	2.4 mm (0.094")	4.0 ±0.10 mm (0.157 ±0.004")	4.0 ±0.1 mm (0.156 ±0.004")	2.0 ±0.1 mm (0.079 ±0.002")	25 mm (0.98")	0.3 ±0.05 mm (0.01 +0.0038/ -0.0002")	8.0 ±0.3 mm (0.315 ±0.012")

<sup>1.</sup> Metric Dimensions Govern-English are in parentheses for reference only.

<sup>2.</sup> A<sub>0</sub>, B<sub>0</sub>, and K<sub>0</sub> are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

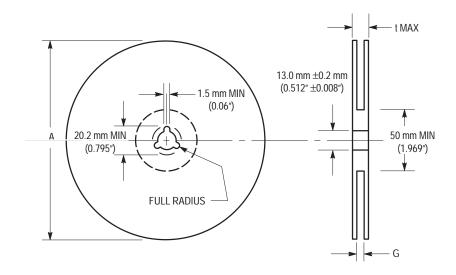


Figure 6. Reel Dimensions

#### **REEL DIMENSIONS**

Tape Size	T&R Suffic	A Max	G	t Max
8 mm	T1, T2	178 mm (7")	8.4 mm, +1.5 mm, -0.0 (0.33" + 0.059", -0.00)	14.4 mm (0.56")
8 mm	R2	330 mm (13")	8.4 mm, +1.5 mm, -0.0 (0.33" + 0.059", -0.00)	14.4 mm (0.56")

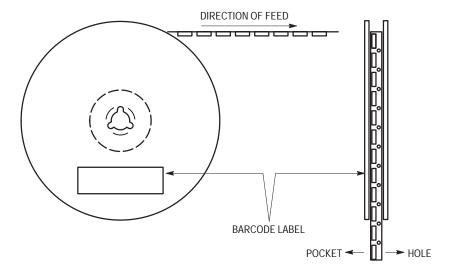


Figure 7. Reel Winding Direction

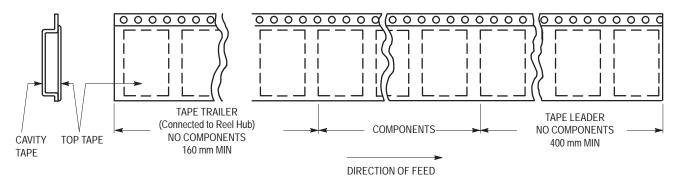


Figure 8. Tape Ends for Finished Goods

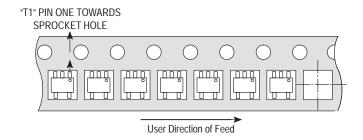


Figure 9. T1 Reel Configuration

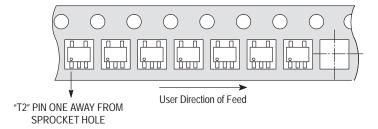
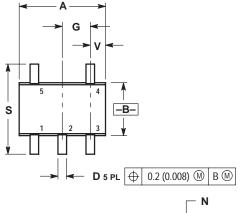
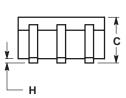


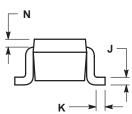
Figure 10. T2 Reel Configuration

#### SC-88A / SOT-353 / SC-70 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-01 ISSUE B

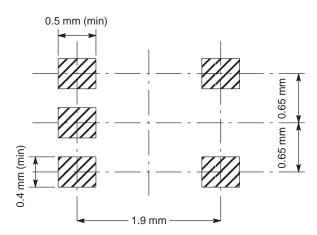






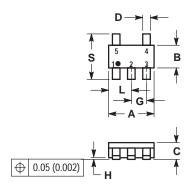
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MM.

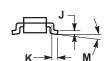
	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20
٧	0.012	0.016	0.30	0.40



#### TSOP-5 / SOT-23 / SC-59 **DT SUFFIX**

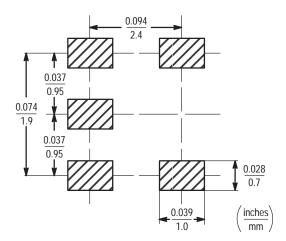
5-LEAD PACKAGE CASE 483-01 ISSUE A





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.00	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0 °	10°	0°	10°
S	2.50	3.00	0.0985	0.1181



# **Notes**

# **Notes**

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